

JL7096E Datasheet

Zhuhai Jieli Technology Co.,LTD

Version 1.1

Date 2025.07.14

Copyright © Zhuhai Jieli Technology Co.,LTD. All rights reserved.

Revision History

Date	Revision	Description
2025.06.04	V1.0	Initial Release
2025.07.14	V1.1	Update Features_SYSTEM

Table of Contents

Revision History	1
Table of Contents	2
JL7096E Features	3
1 Block Diagram	5
2 Pin Definition	6
2.1 Pin Assignment	6
2.2 Pin Description	7
3 Electrical Characteristics	9
3.1 Absolute Maximum Ratings	9
3.2 ESD Ratings	9
3.3 PMU Characteristics	9
3.4 Battery Charge	10
3.5 IO Characteristics	10
3.6 Audio DAC Characteristics	11
3.7 Audio ADC Characteristics	12
3.8 BT Characteristics	14
4 Package Information	15
4.1 QFN32_4x4mm	15
5 IC Marking Information	16
6 Solder-Reflow Condition	17

JL7096E Features

SYSTEM

- Dual Core 32bit DSP 192MHz
- With IEEE754 Single precision FPU
- Support FFT/MATRIX/MATH
- 2 x I-cache and D-cache
- Support SDTAP/EMU
- On-chip SRAM 320kbyte
- Support MMU
- Support MPU
- Built-In Flash
- 24MHz crystal oscillator
- Internal RC oscillator, PLL

DSP Audio Processing

- SBC/AAC/LDAC/LHDC/LC3/CVSD/mSBC codec
- mSBC voice codec supported for BT phone
- PLC for voice processing
- Single/Multi MIC ENC
- Multi-band DRC
- Multi-band EQ
- Support spatial sound
- Support assistive listening
- Support Hi-Res Audio

ANC

- Wide band digital adaptive ANC
- Support hybrid/feedforward/feedback
- Support wind noise detection
- Support wide area tap
- Support Speak-to-Chat
- Support tip fit test & wear detection
- Input-to-output latency < 8us

Audio

- 1 x 24bit DAC
 - ❖ SNR 113dB
 - ❖ Noise 1.2uVrms
 - ❖ Supports differential mode
 - ❖ Sampling rate 8~384kHz
- 3 x 24bit ADC
 - ❖ SNR 103dB

- ❖ Sampling rate 8~192kHz

- I²S/TDM/PDM/SPDIF AUDIO Master/Slave interface

Bluetooth

- Dual-mode BT6.0 with LE Audio (DN Q332415)
- Support AoA/AoD
- Support LE audio BIS/CIS
- Maximum transmitting power 13dBm
- Receiver sensitivity
 - ❖ -97dBm @BR
 - ❖ -97dBm @EDR $\pi/4$ DQPSK
 - ❖ -89dBm @EDR 8DPSK

Peripherals

- 1 x Full speed USB
- 1 x SD host controller
- 6 x Multi-function 32bit timer
- 3 x UART interface
- 1 x I²C Master/Slave interface
- 3 x SPI Master/Slave interface
- 1 x QDEC
- 2 x Light strip controller
- 1 x 10bit ADC(9 Channels)
- 4 x MCPWM
- 1 x CAN controller
- 16 x GPIO Support function remapping
- 5 x LP_Touch with low power wake up

PMU

- Integrated battery charger up to 180mA
- 2 x Buck DC-DC converter
- Support temperature sensor
- VPWR range 4.5V to 5.5V
- VBAT range 2.7V to 4.5V
- IOVDD range 2.7V to 3.6V

Packages

- QFN32(4*4mm)

Temperature

- Operating temperature
TC = -20℃ to +85℃ (standard range)
TC = -40℃ to +105℃ (extended range)
- Storage temperature -65℃ to +150℃

Applications

- Adaptive ANC TWS
- Bluetooth audio device

1 Block Diagram

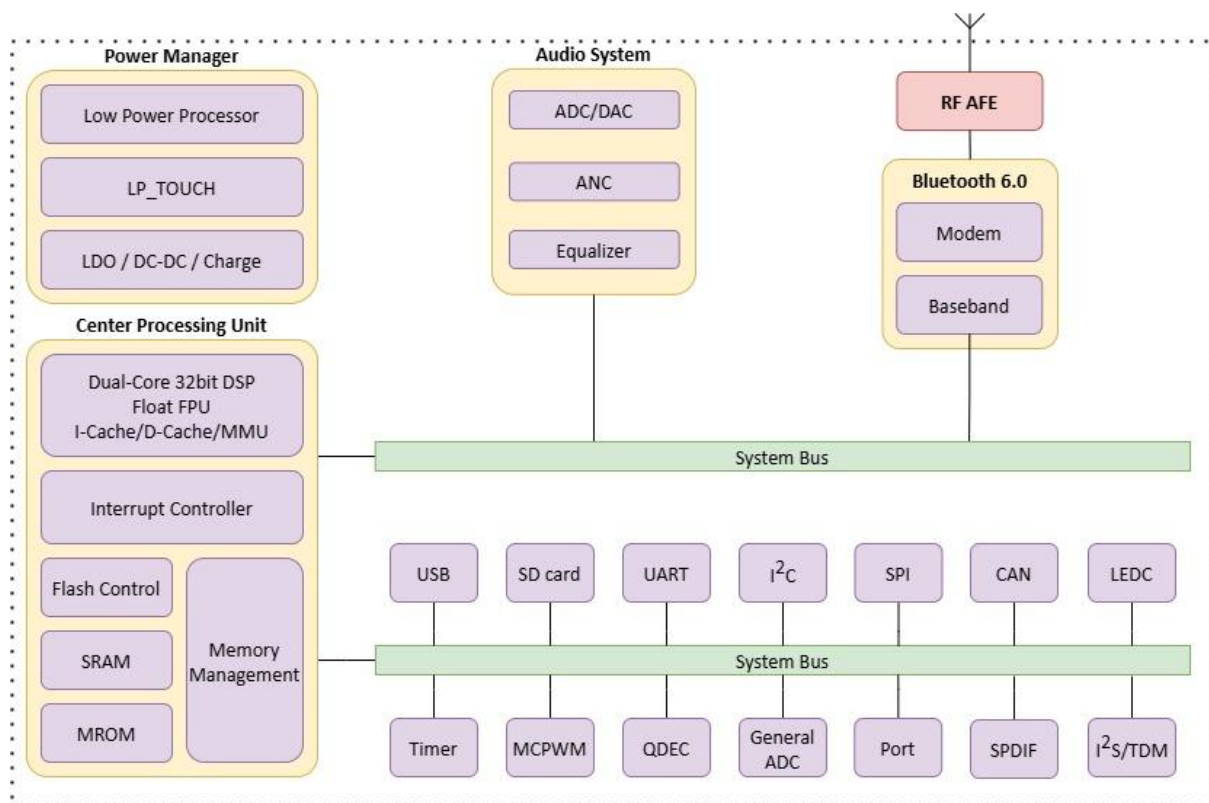


Figure 1-1 JL7096E Block Diagram

2 Pin Definition

2.1 Pin Assignment

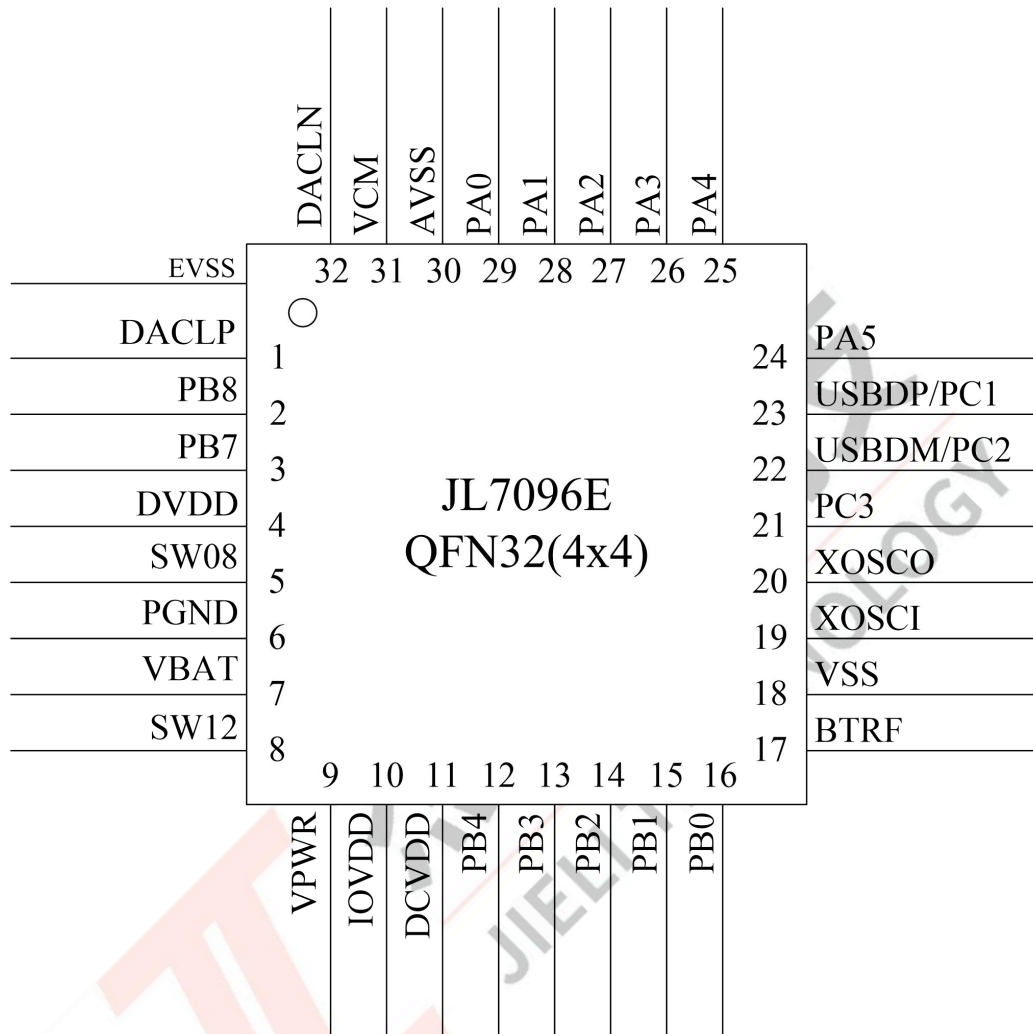


Figure 2-1 JL7096E Pin Assignment

2.2 Pin Description

Table 2-2-1 JL7096E Pin Description

Pin No.	Name	Type	IO Initial State	Description
1	DACLP	O	--	Left Channel DAC Positive Output
2	PB8	I/O	Z	AIN_CP0(Audio ADC Positive Input)
3	PB7	I/O	Z	AIN_CN0(Audio ADC Negative Input)
4	DVDD	P	--	Buck DCDC08 Output Power
5	SW08	P	--	Buck DCDC08 Switch Port
6	PGND	P	--	Ground of Buck DC-DC converter
7	VBAT	P	--	Battery Input
8	SW12	P	--	Buck DCDC12 Switch Port
9	VPWR	I/O	Z	Charge Power Input
10	IOVDD	P	--	IO Power
11	DCVDD	P	--	Buck DCDC12 Output Power
12	PB4	I/O	Z	ADC4(ADC Input Channel 4) LP_TOUCH4(TOUCH_CH4)
13	PB3	I/O	Z	ADC3(ADC Input Channel 3) LP_TOUCH3(TOUCH_CH3)
14	PB2	I/O	Z	ADC2(ADC Input Channel 2) LP_TOUCH2(TOUCH_CH2)
15	PB1	I/O	10kΩ Pull-up	ADC1(ADC Input Channel 1) LP_TOUCH1(TOUCH_CH1) Hold down 0 to reset
16	PB0	I/O	Z	ADC0(ADC Input Channel 0) LP_TOUCH0(TOUCH_CH0)
17	BTRF	RF	--	Bluetooth RF Antenna
18	VSS	G	--	Ground
19	XOSCI	I	--	Crystal Oscillator Input
20	XOSCO	O	--	Crystal Oscillator Output
21	PC3	I/O	Z	ADC9(ADC Input Channel 9) SPDIF_VIN2
22	PC2	I/O	Z	ADC8(ADC Input Channel 8) SPDIF_VIN1
	USBDM	I/O	15kΩ Pull-down	USB Negative Data ADC15(ADC Input Channel 15)
23	PC1	I/O	Z	ADC7(ADC Input Channel 7) SPDIF_VIN0
	USBDP	I/O	15kΩ Pull-down	USB Positive Data ADC14(ADC Input Channel 14)
24	PA5	I/O	Z	AIN_BP0(Audio ADC Positive Input)

Pin No.	Name	Type	IO Initial State	Description
25	PA4	I/O	Z	AIN_BN0(Audio ADC Negative Input) AIN_AN1(Audio ADC Negative Input)
26	PA3	I/O	Z	AIN_AP1(Audio ADC Positive Input) MICBIASB(MIC Bias Output)
27	PA2	I/O	Z	AIN_AN0(Audio ADC Negative Input)
28	PA1	I/O	Z	AIN_AP0(Audio ADC Positive Input)
29	PA0	I/O	Z	ADC6(ADC Input Channel 6) MICBIASA(MIC Bias Output) MICLDO(MIC Bias LDO Output)
30	AVSS	G	--	Audio Ground
31	VCM	P	--	Audio reference voltage
32	DACLN	O	--	Left Channel DAC Negative Output

Note

- 1.IO initial state abbreviations Z--High resistance, H--High level, L--Low level, X--May be changed during power on.
- 2.Timer, SPDIF, MCPWM, QDEC, UART, LEDC, I²C, I²S, SPI, CAN and SD functions can be remapped to any I/O.

Table 2-2-2 Pin Types Description

Pin Type	Description	Pin Type	Description
P	Power	I/O	Input or Output
G	Ground	I	Input
RF	RF antenna	O	Output

3 Electrical Characteristics

3.1 Absolute Maximum Ratings

Table 3-1 Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit
T _{opt}	Operating temperature	-20	+85	°C
T _{stg}	Storage temperature	-65	+150	°C
VBAT	Supply Voltage	-0.3	4.5	V
VPWR		-0.3	6	V
IOVDD		-0.3	3.6	V
DCVDD		-0.3	1.25	V
DVDD		-0.3	0.9	V
GPIO	Input voltage of GPIO	-0.3	3.6	V

Note

1. Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device.

3.2 ESD Ratings

Table 3-2 ESD Ratings

Parameter	Typ	Test pin	Reference standard
Human Body Mode	±4kV	All pins	JEDEC EIA/JESD22-A114
Machine Mode	±300V	All pins	JEDEC EIA/JESD22-A115
Charge Device Model	±2kV	All pins	ANSI/ESDA/JEDEC JS-002-2022

3.3 PMU Characteristics

Table 3-3 PMU Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VBAT	Power supply	--	2.7	3.7	4.5	V
VPWR	Power supply	--	4.5	5.0	5.5	V
Operating mode						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
IOVDD	Voltage output	--	--	3	--	V
	Loading current	IOVDD=3.0V@VBAT = 3.7V or VPWR=5V	--	--	120	mA
DCVDD	Voltage output	--	--	1.15	--	V
	Loading current	DCVDD=1.15V@IOVDD=3.0V in LDO mode	--	--	120	mA
		DCVDD=1.15V@VBAT=3.7V in DCDC mode	--	--	120	mA
Low Power mode						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit

IOVDD	Loading current	IOVDD=3.0V@VBAT = 3.7V or VPWR=5V	--	--	10	mA
-------	-----------------	-----------------------------------	----	----	----	----

3.4 Battery Charge

Table 3-4 Charger Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
VPWR	Charge Input Voltage	4.5	5	5.5	V
CV	CV Mode Voltage Accuracy	4.175	4.2	4.225	V
		4.325	4.35	4.375	V
CC	CC Mode Current	15	--	180	mA
I _{end}	End Of Charge Current	1.5	--	18	mA
V _{Trickl}	Trickle Charge Voltage	--	3	--	V

3.5 IO Characteristics

Table 3-5 IO Characteristics

Input Characteristics						
Symbol	Parameter	Conditions	IO	Min	Max	Unit
V _{IL}	Low-Level Input Voltage	IOVDD = 3.0V	PA0~PA5 PB0~PB4,PB7,PB8 PC1~PC3 USBDP USBDM VPWR	-0.3	1.4	V
V _{IH}	High-Level Input Voltage	IOVDD = 3.0V	PA0~PA5 PB0~PB4,PB7,PB8 PC1~PC3 USBDP USBDM	1.7	3.3	V
		IOVDD = 3.0V	VPWR	1.7	5.5	V
Output Characteristics						
Symbol	Parameter	Conditions	IO	Typ	Unit	
I _{OL}	Output Current	IOVDD = 3.0V Voutput = 0.3V	PA0~PA5 PB0~PB4,PB7,PB8 PC1~PC3	4(HD=0) 8(HD=1) 16(HD=2) 32(HD=3)	mA	
		IOVDD = 3.0V Voutput = 0.3V	USBDP USBDM	8	mA	
		IOVDD = 3.0V Voutput = 0.3V	VPWR	2	mA	
I _{OH}	Output Current	IOVDD = 3.0V Voutput = 2.7V	PA0~PA5 PB0~PB4,PB7,PB8	4(HD=0) 8(HD=1)	mA	

			PC1~PC3	16(HD=2) 32(HD=3)	
		IOVDD = 3.0V Voutput = 2.7V	USBDP USBDM	8	mA
		IOVDD = 3.0V Voutput = 2.7V	VPWR	2	mA
Internal Resistance Characteristics					
Symbol	Parameter	Conditions	IO	Typ	Unit
R _{pu}	Pull-up Resistance	IOVDD = 3.0V	PA0~PA5 PB0~PB4,PB7,PB8 PC1~PC3 VPWR	10k(PU=1) 100k(PU=2) 1M(PU=3)	Ω
		IOVDD = 3.0V	USBDP	1.5k	Ω
		IOVDD = 3.0V	USBDM	180k	Ω
R _{pd}	Pull-down Resistance	IOVDD = 3.0V	PA0~PA5 PB0~PB4,PB7,PB8 PC1~PC3 VPWR	10k(PD=1) 100k(PD=2) 1M(PD=3)	Ω
		IOVDD = 3.0V	USBDP USBDM	15k	Ω

Note

1.Internal pull-up/pull-down resistance accuracy $\pm 20\%$

3.6 Audio DAC Characteristics

Table 3-6 DAC Characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Resolution	--	--	24	--	bits
Input Sample Rate	--	8	--	384	kHz
SNR ^①	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	113	--	dB
Dynamic Range	Differential Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	106	--	dB
THD+N	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz	--	-85	--	dB

Parameter	Conditions	Min	Typ	Max	Unit
	B/W=20Hz~20kHz A-Weighted Load=32Ω				
Noise Floor	Differential Mode B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	2.7	--	uVrms
Noise Floor with MUTE	Differential Mode B/W=20Hz~20kHz A-Weighted Load=10kΩ	--	1.2	--	uVrms
Max Output Power	Differential Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted Load=16Ω THD+N<1%	--	20	30	mW

Note

- ① SNR is the ratio of output level with a 1kHz full-scale input to output level with MUTE on.

3.7 Audio ADC Characteristics

Table 3-7 Audio ADC Characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Resolution	--	--	24	--	bits
Output Sample Rate	--	8	--	192	kHz
SNR	Differential input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	103	--	dB
	Single-ended input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	100	--	dB
Dynamic Range	Differential input Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	103	--	dB
	Single-ended input Mode Fin=1kHz@-60dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted	--	100	--	dB

Parameter	Conditions	Min	Typ	Max	Unit
	ADC gain=0dB				
THD+N	Differential input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	-85	--	dB
	Single-ended input Mode Fin=1kHz@0dBFS Fs=44.1kHz B/W=20Hz~20kHz A-Weighted ADC gain=0dB	--	-83	--	dB
Analogue Gain	--	-6	--	27	dB
Max Input Level	Differential input Mode ADC gain=0dB	--	0.56	--	Vrms
	Single-ended input Mode ADC gain=0dB	--	0.28	--	Vrms

3.8 BT Characteristics

3.8.1 Transmitter

Table 3-8-1 Transmitter characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Maximum RF Transmit Power	BR	--	10	13	dBm
Maximum RF Transmit Power	EDR $\pi/4$ DQPSK EDR 8DPSK	--	10	--	dBm
Relative Transmit Power	EDR $\pi/4$ DQPSK EDR 8DPSK	--	3	--	dB
Maximum RF Transmit Power	BLE-1Mbps	--	10	13	dBm

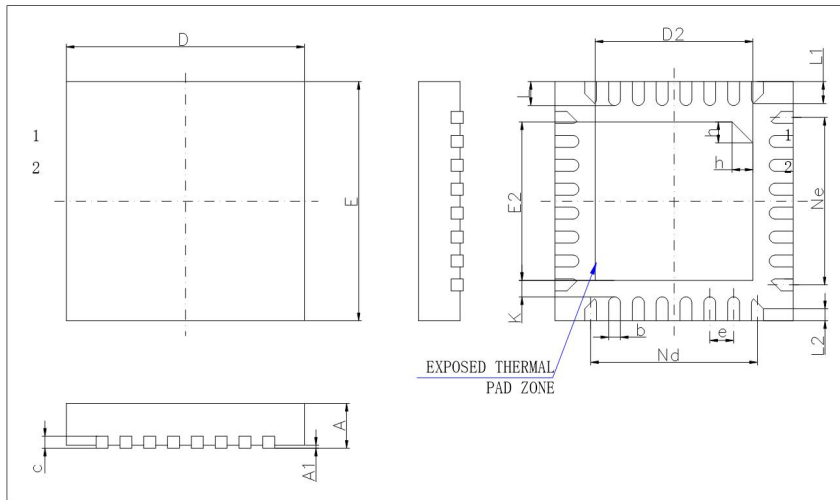
3.8.2 Receiver

Table 3-8-2 Receiver characteristics

Parameter	Conditions	Min	Typ	Max	Unit
Sensitivity	BR	--	-97	--	dBm
	EDR $\pi/4$ DQPSK	--	-97	--	dBm
	EDR 8DPSK	--	-89	--	dBm
	BLE-1Mbps	--	-99.5	--	dBm
	BLE-2Mbps	--	-96.5	--	dBm

4 Package Information

4.1 QFN32_4×4mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.65	0.80	0.95
A1	0	0.02	0.05
b	0.15	0.20	0.25
c	0.18	0.20	0.25
D	3.90	4.00	4.10
D2	2.50	2.65	2.80
e	0.40BSC		
Nd	2.80BSC		
E	3.90	4.00	4.10
E2	2.50	2.65	2.80
Ne	2.80BSC		
K	0.20	-	-
L	0.35	0.40	0.45
L1	0.30	0.35	0.40
L2	0.15	0.20	0.25
h	0.30	0.35	0.40
L/F 载体尺寸 (mil)	112*112		

Figure 4-1 JL7096E Package

5 IC Marking Information

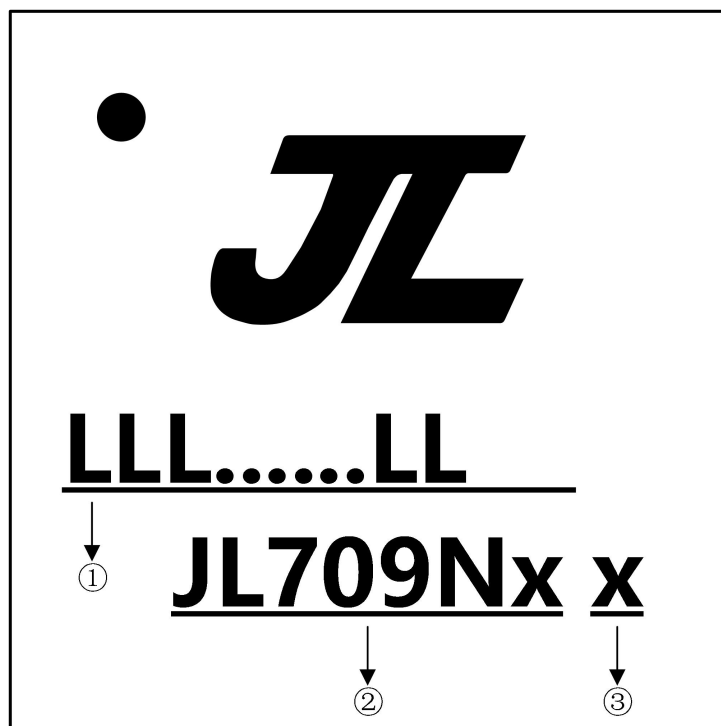


Figure 5-1 JL7096E Package Outline

- ① LLL.....LL LOT No. , It contains 7 to 18 alphanumerics
- ② JL709Nx Chip Model
- ③ x : Built-in flash size
 - 0 : No Flash Memory
 - 2 : 2Mbit Flash
 - 4 : 4Mbit Flash
 - 8 : 8Mbit Flash
 - 6 : 16Mbit Flash
 - 3 : 32Mbit Flash

6 Solder-Reflow Condition

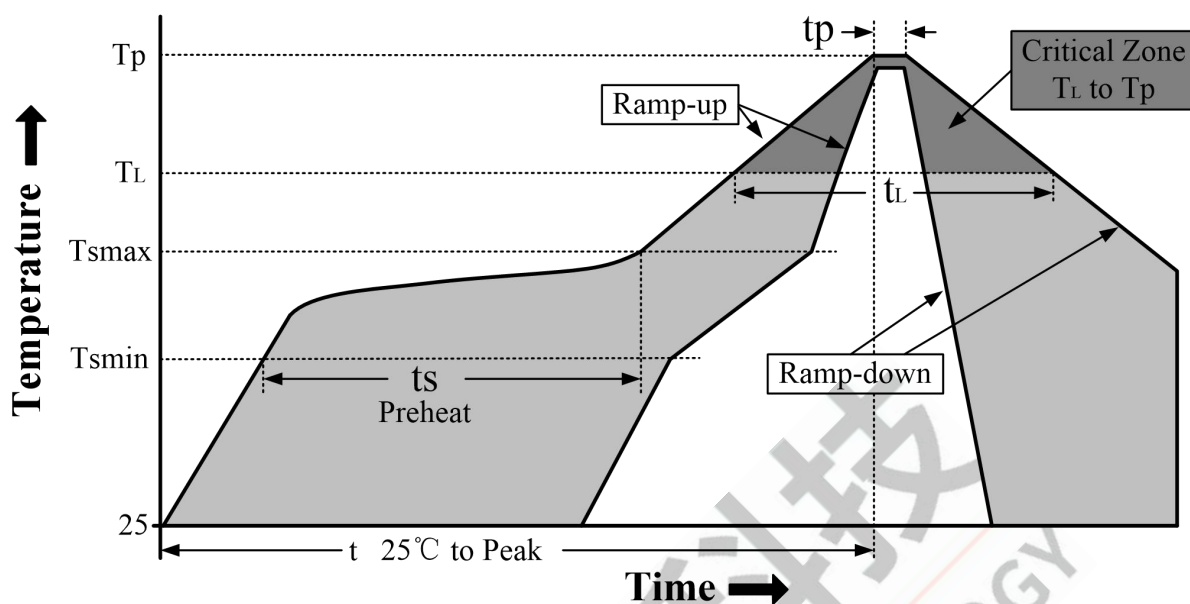


Figure 6-1 Classification Reflow Profile

Table 6-1 Classification Profiles

Profile Feature		Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/Soak	Temperature Min (T_{smin})	100°C	150°C
	Temperature Max (T_{smax})	150°C	200°C
	Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-180 seconds
Average ramp-up rate (T_{smax} to T_p)		3°C/second max	3°C/second max
Liquidous temperature (T_L)		183°C	217°C
Time (t_L) maintained above T_L		60-150 seconds	60-150 seconds
Peak package body temperature (T_p)		See Table 6-2	See Table 6-3
Time within 5°C of actual Peak Temperature (t_p) ²		10-30 seconds	20-40 seconds
Ramp-down rate (T_p to T_L)		6°C/second max	6°C/second max
Time 25°C to peak temperature		6 minutes max	8 minutes max

Note

- 1.All temperatures refer to topside of the package, measured on the package body surface
- 2.Time within 5°C of actual peak temperature (t_p) specified for the reflow profiles is a "supplier" and "user" maximum.

Table 6-2 SnPb Classification Temperature

Package Thickness	Volume mm ³ < 350	Volume mm ³ ≥ 350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5°C

Table 6-3 Pb-free - Classification Temperature

Package Thickness	Volume mm ³ < 350	Volume mm ³ 350 - 2000	Volume mm ³ > 2000
< 1.6mm	260°C	260°C	260°C
1.6 mm - 2.5mm	260°C	250°C	245°C
> 2.5mm	250°C	245°C	245°C

Note

1.*Tolerance The device manufacturer/supplier shall assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0°C.For example 260°C+0°C)at the rated MSL level.